

## **Job Posting:171892 - Position: F25 Application Engineer Co-op 171892**

<b>Co-op Work Term Posted:</b>	2025 - Fall
<b>App Deadline</b>	08/20/2025 09:00 AM
<b>Application Method:</b>	Through UBC Science Co-op
<b>Posting Goes Live:</b>	08/13/2025 12:03 PM
<b>Job Posting Status:</b>	Approved

## **ORGANIZATION INFORMATION**

<b>Organization</b>	GaNPower International
<b>Address Line 1</b>	230-3410 Lougheed Hwy,
<b>City</b>	Vancouver
<b>Postal Code / Zip Code</b>	V5M 2A4
<b>Province / State</b>	British Columbia
<b>Country</b>	Canada

## **JOB POSTING INFORMATION**

<b>Placement Term</b>	2025 - Fall
<b>&lt;b&gt; Job Title &lt;/b&gt;</b>	F25 Application Engineer Co-op 171892
<b>Position Type</b>	Co-op Position
<b>Job Location</b>	Vancouver, BC
<b>Country</b>	Canada
<b>Duration</b>	4 or 8 months
<b>Work Mode</b>	In-Person
<b>Salary Currency</b>	CAD
<b>Salary</b>	3300.0 per month for 38 Major List
<b>Job Description</b>	

### **Company Introduction**

GaNPower is dedicated to developing power electronic technology based on Gallium Nitride (GaN). We believe that GaN power semiconductors have the potential to revolutionize the efficient use of electrical energy. If you are eager to contribute to a sustainable future by generating leading edge innovation, then this is your chance!

### **Job description**

In this role, you will decisively contribute to the development of our next-generation all-GaN intelligent power module (IPM) technology, ranging from device concept engineering and board-level reliability assessment to production ramp-up.

- **Hardware Integration Support:** Support the integration of a co-packaged Analog-to-Digital Converter (ADC) module by helping to design and validate the system under high-speed switching conditions.
- **Firmware and Algorithm Development:** Develop and test firmware calibration algorithms for the IPM's temperature compensation strategy.
- **IC Validation and Testing:** Execute high-current double pulse tests (DPTs), 500/1,000-hour power cycling reliability runs, and perform electromagnetic compatibility pre-scans.
- **Printed Circuit Board (PCB) Assembly:** Assemble and solder PCBs, assisted by understanding and following electrical schematics and bills of materials (BOM).
- **Additional Responsibilities:** May include device testing, circuit simulation on LTspice, as well as PCB testing and debugging.

**Number of working hours per week:** 38-40 hours

## **Job Requirements**

### **Requirements:**

- Currently enrolled in a 3rd/4th year program in electrical engineering, computer engineering, engineering physics, or other relevant fields.
- Proficiency in programming, preferably in C / C++, for embedded systems.
- Prior experience with ADCs and microcontrollers such as the Microchip PIC32 series or TI C2000 series.
- Hands-on experience with engineering lab equipment such as oscilloscopes, multimeters, and power supplies.
- Behavioral skills such as ability to work well independently, as well as in a team, multitasking, good organizational and documentation skills.

### **Assets:**

- Experience in semiconductor testing, especially power device characterization, is a strong asset.
- Familiarity with circuit simulation tools like LTspice.
- Experience with thermal testing or the use of a climatic chamber.
- Understanding of power electronics topologies and high-voltage Si, SiC, or GaN devices.

**Citizenship Requirement**      N/A

## **APPLICATION INFORMATION**

**Application Procedure**      Through UBC Science Co-op

**Cover Letter Required?**      Optional

**Address Cover Letter to**      Heemal Parimoo

### **Special Application Instructions**

Please include a portfolio if you have one showcasing relevant projects, professional work, or university coursework.